Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$	I_D T_A = 25°C
20V	3.0Ω @ V_{GS} = 4.5V	240mA
	6.0Ω @ V_{GS} = 1.8V	170mA

Description and Applications

This new generation MOSFET has been designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- Power management functions

Features and Benefits

- N-Channel MOSFET
- Low On-Resistance:
  - 3.0 Ω @ 4.5V
  - 4.0 Ω @ 2.5V
  - 6.0 Ω @ 1.8V
  - 10 Ω @ 1.5V
- Very Low Gate Threshold Voltage, 1.05V max
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package, 0.4mm Maximum Package Height
- ESD Protected Gate
- **Lead, Halogen and Antimony Free, RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**

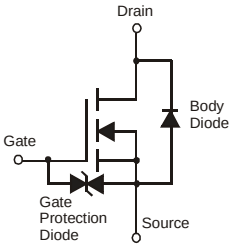
Mechanical Data

- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.001 grams (approximate)

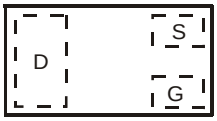
ESD PROTECTED

X2-DFN1006-3

Bottom View



Equivalent Circuit



Top View

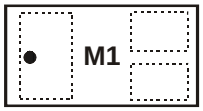
Ordering Information (Note 3)

Part Number	Case	Packaging
DMN26D0UFB4-7	X2-DFN1006-3	3,000/Tape & Reel
DMN26D0UFB4-7B	X2-DFN1006-3	10,000/Tape & Reel

Notes: 1. No purposefully added lead.
2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
3. For packaging details, go to our website at http://www.diodes.com.

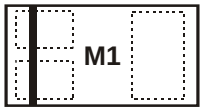
Marking Information

DMN26D0UFB4-7



Top View
Dot Denotes Drain Side

DMN26D0UFB4-7B



Top View
Bar Denotes Gate and Source Side

M1 = Product Type Marking Code

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain Source Voltage			V_{DSS}	20	V
Gate-Source Voltage			V_{GSS}	±10	V
Continuous Drain Current (Note 4) V_{GS} = 4.5V	Steady State	T_A = 25°C T_A = 70°C	I_D	240 190	mA
Continuous Drain Current (Note 4) V_{GS} = 1.8V	Steady State	T_A = 25°C T_A = 70°C	I_D	180 140	mA
Pulsed Drain Current - T_P = 10µs			I_{DM}	805	mA

Thermal Characteristics @T_A = 25°C unless otherwise specified

Total Power Dissipation (Note 4) @T_A = 25°C	P_D	350	mW
Thermal Resistance, Junction to Ambient (Note 4)	$R_{\theta JA}$	357	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV_{DSS}	20	—	—	V	V_{GS} = 0V, I_D = 100µA
Zero Gate Voltage Drain Current @ T_C = 25°C	I_{DSS}	—	—	500	nA	V_{DS} = 20V, V_{GS} = 0V
Gate-Body Leakage	I_{GSS}	—	—	±1 ±100	µA nA	V_{GS} = ±10V, V_{DS} = 0V V_{GS} = ±5V, V_{DS} = 0V
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	$V_{GS(th)}$	0.45	—	1.05	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS\ (ON)}$	— — — —	1.8 2.5 3.4 4.7	3.0 4.0 6.0 10.0	Ω	V_{GS} = 4.5V, I_D = 100mA V_{GS} = 2.5V, I_D = 50mA V_{GS} = 1.8V, I_D = 20mA V_{GS} = 1.5V, I_D = 10mA
Forward Transconductance	$\|Y_{fs}\|$	180	242	—	mS	V_{DS} = 10V, I_D = 0.1A
Source-Drain Diode Forward Voltage	V_{SD}	0.5	—	1.4	V	V_{GS} = 0V, I_S = 115mA
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	—	14.1	—	pF	V_{DS} = 15V, V_{GS} = 0V f = 1.0MHz
Output Capacitance	C_{oss}	—	2.9	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	1.6	—	pF	
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	$t_{d(on)}$	—	3.8	—	ns	V_{GS} = 4.5V, V_{DD} = 10V I_D = 200mA, R_G = 2.0Ω
Rise Time	t_r	—	7.9	—		
Turn-Off Delay Time	$t_{d(off)}$	—	13.4	—		
Fall Time	t_f	—	15.2	—		

Notes: 4. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
5. Short duration pulse test used to minimize self-heating effect.

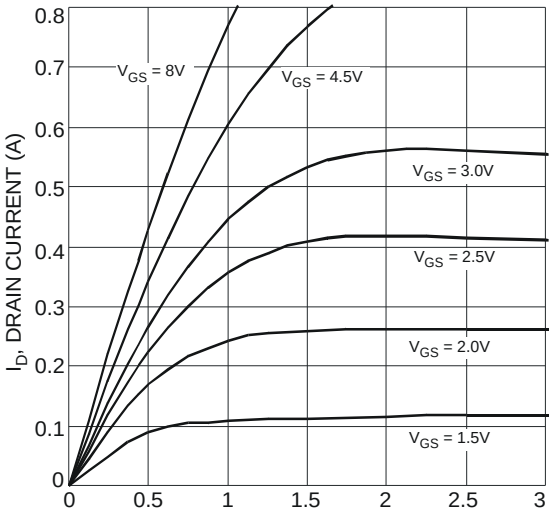


Fig. 1 Typical Output Characteristic

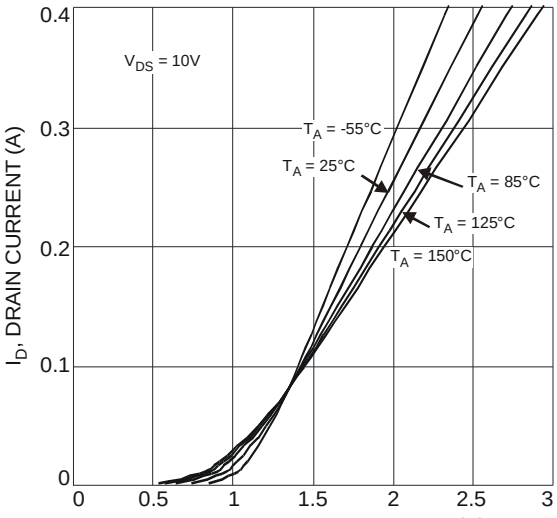


Fig. 2 Typical Transfer Characteristic

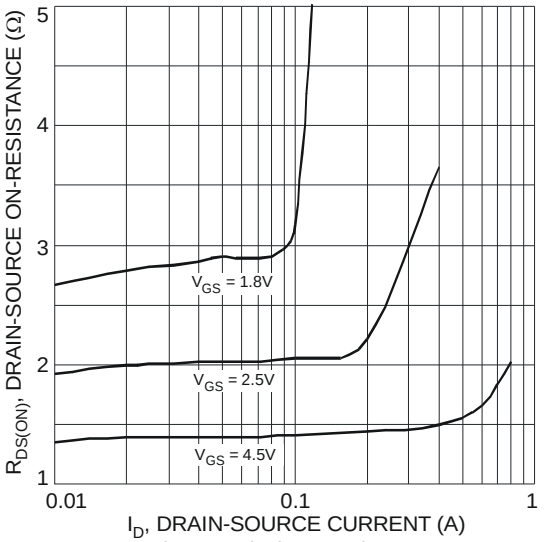


Fig. 3 Typical On-Resistance
vs. Drain Current and Gate Voltage

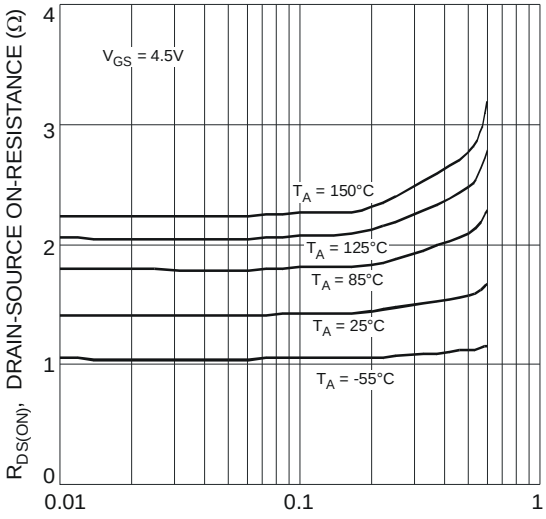


Fig. 4 Typical On-Resistance
vs. Drain Current and Temperature

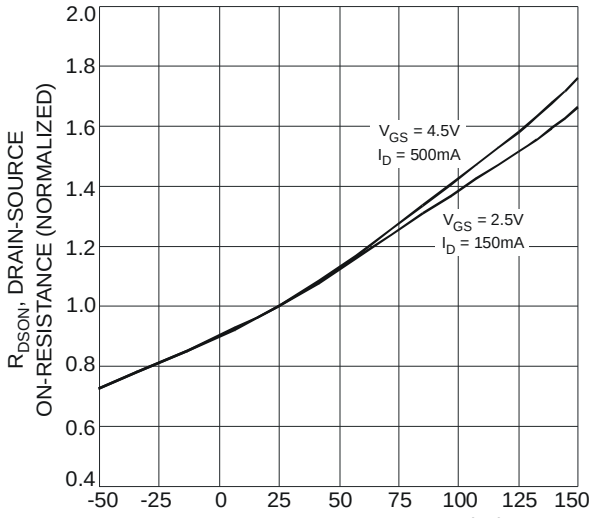


Fig. 5 On-Resistance Variation with Temperature

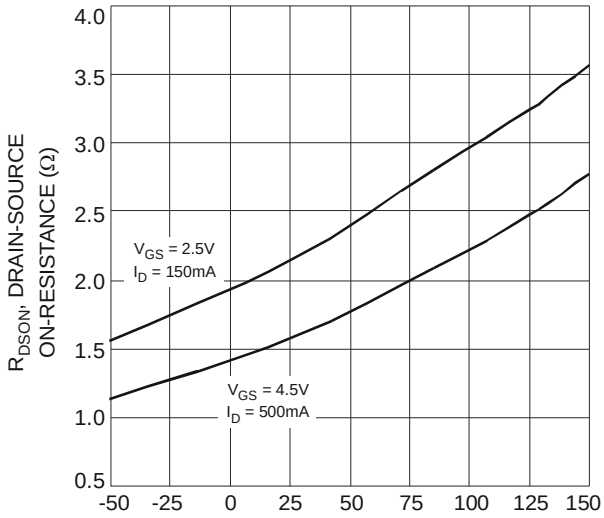


Fig. 6 On-Resistance Variation with Temperature

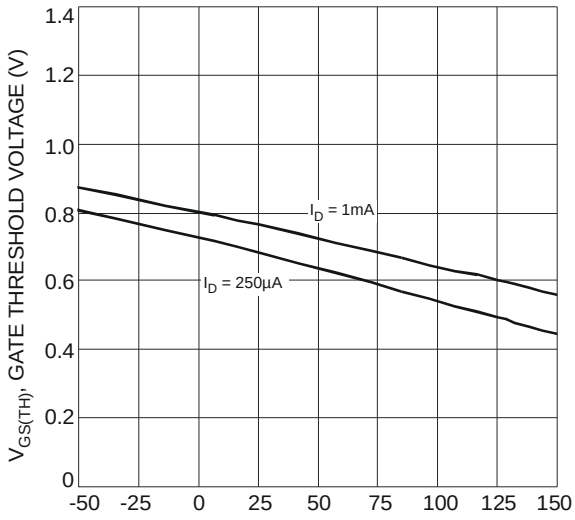


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

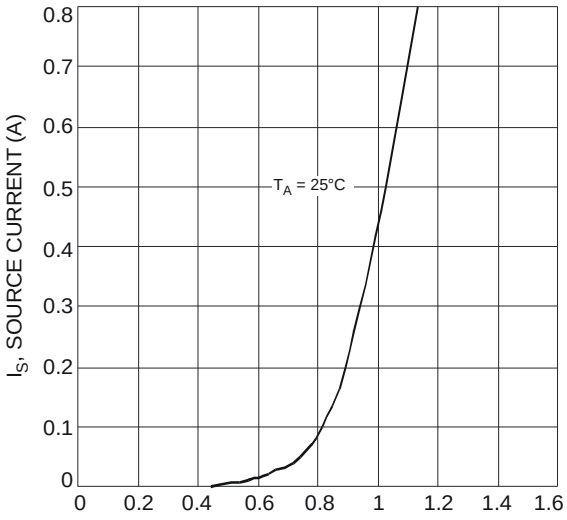


Fig. 8 Diode Forward Voltage vs. Current

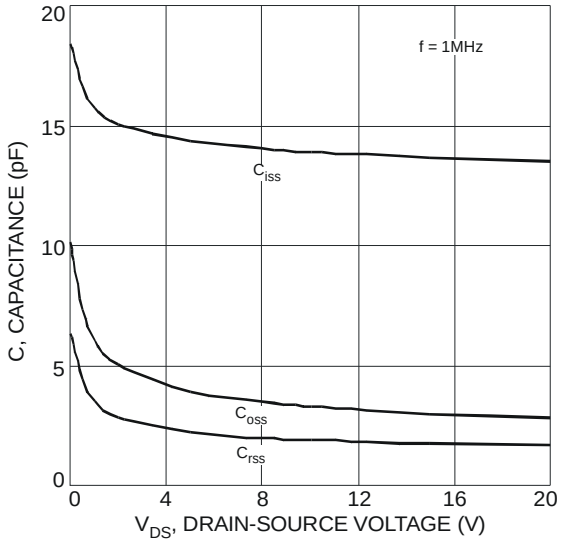


Fig. 9 Typical Total Capacitance

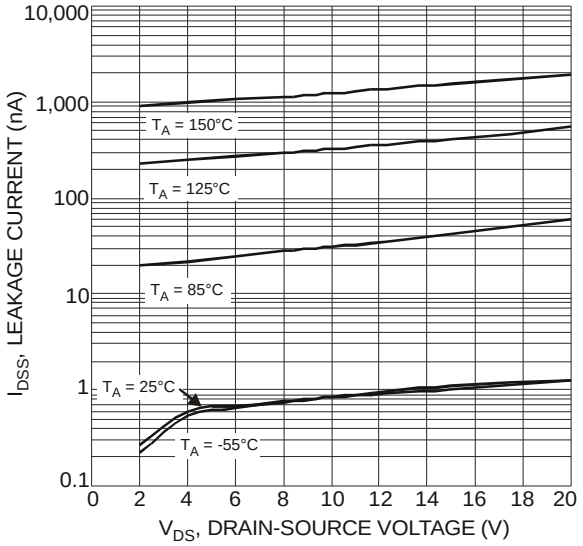


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

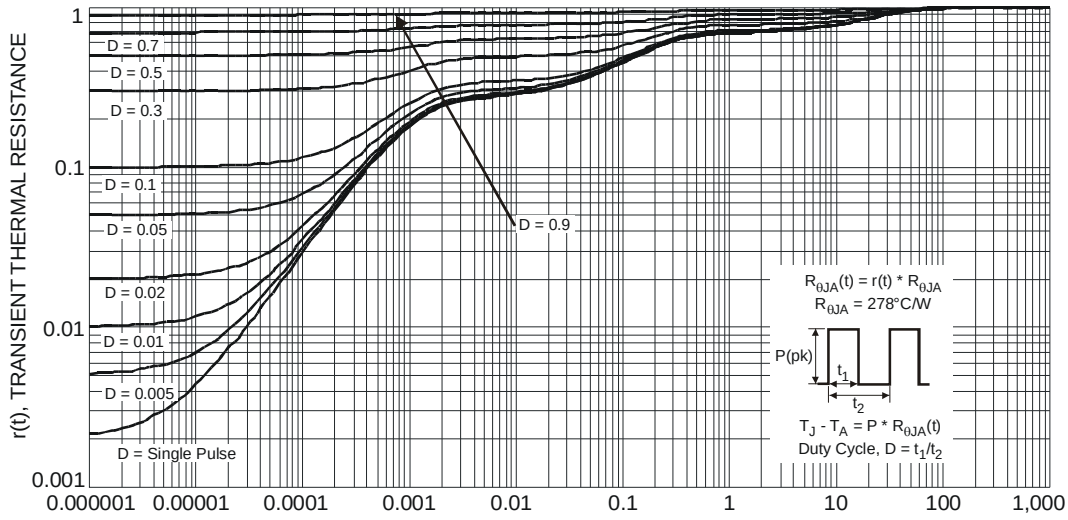
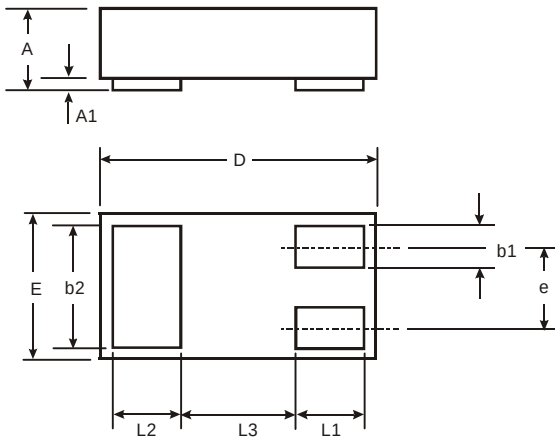


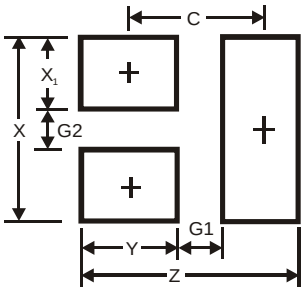
Fig. 11 Transient Thermal Response

Package Outline Dimensions



X2-DFN1006-3			
Dim	**Min**	**Max**	**Typ**
A	—	0.40	—
A1	0	0.05	0.02
b1	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.05	1.00
E	0.55	0.65	0.60
e	—	—	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	—	—	0.40
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

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- Подбор аналогов;
- Консультации по применению компонента;
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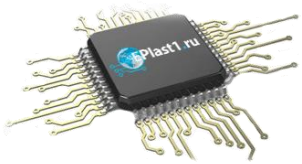
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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